



Title of Change:	Fab Transfer to ON Semiconductor Gresham, Oregon as wafer fab location for NCV7471DQ5R2G, NCV7471ADQ5R2G, NCV7471BDQ5R2G and NCV7471CDQ5R2G – currently manufactured in ON Semiconductor Fab10, Pocatello. In addition we will convert to Cu Wire.	
Proposed Changed Material First Ship Date:	20 Feb 2021 or earlier if approved by customer	
Current Material Last Order Date:	18 Dec 2020 <i>Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.</i>	
Current Material Last Delivery Date:	19 Feb 2021 <i>The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory</i>	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local ON Semiconductor Sales Office or Alicia.Tuckett@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	15 May 2020	
PPAP Availability Date:	18 Dec 2020	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Dimitri.Tack@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor Change of gate material / dielectrics	
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.	
Process - Assembly	Change of wire bonding	
Description and Purpose:		
Fab Transfer to ON Semiconductor Gresham, Oregon as wafer fab location for NCV7471DQ5R2G, NCV7471ADQ5R2G, NCV7471BDQ5R2G and NCV7471CDQ5R2G – currently manufactured in ON Semiconductor Fab10, Pocatello. In addition we will convert to Cu Wire.		
	Before Change Description	After Change Description
Fab Transfer	Fab10, Pocatello, Idaho	Gresham, Oregon
Bond Wire	Au	PdCu (Paladium Copper)



Reason / Motivation for Change:	Quality improvement	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
- Internal Site not in list -	None	
ON Semiconductor Carmona, Philippines		
Marking of Parts/ Traceability of Change:	The affected products will be identified with date code.	
Reliability Data Summary: AEC-1 pager for NCV7471DQ5R2G with Pd coated Cu wires (PCC) and wafer manufacturing in Gresham (Oregon) is attached. Qualification and AEC-1 pager for NCV7471BDQ5R2G and NCV7471CDQ5R2G, processed with proposed change, will be finalized and provided before the proposed change material first ship date <i>To view attachments:</i> 1. Download pdf copy of the PCN to your computer 2. Open the downloaded pdf copy of the PCN 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field 4. Then click on the attached file/s		
Electrical Characteristics Summary: Electrical characteristics are not impacted.		
List of Affected Parts: Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.		
Current Part Number	New Part Number	Qualification Vehicle
NCV7471DQ5R2G	NCV7471CDQ5R2G	NCV7471CDQ5R2G
NCV7471ADQ5R2G	NCV7471CDQ5R2G	NCV7471CDQ5R2G
NCV7471BDQ5R2G	NCV7471BDQ5R2G	NCV7471BDQ5R2G
NCV7471CDQ5R2G	NCV7471CDQ5R2G	NCV7471CDQ5R2G



Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV7471BDQ5R2G		NCV7471BDQ5R2G	NCV7471BDQ5R2G	